Note from Chapter Chair:

Shaw Fong Wong
IEEE CPMT M'sia Chair 2016
Intel Technologies

Greetings to all CPMT M'sia members! Apa khabar semua?

How time flies… the year 2016 has come to a conclusion and it has been an exciting year for many of us in the Malaysia semiconductor business. As shared in 1H of Y2016, the new era of "Things" opened up a myriad of possibilities. A quick gauge to determine where we are in terms of keeping up to speed with technological trends – How many of us have tested or used any of the **10 Useful IoT products** in 2016?? The industry has encountered the need for multiple levels of device integration and mergence complexities. As such, we need to challenge ourselves to produce smaller, faster and cost effective packaging with novel materials in an ever decreasing time cadence.

For CPMT M'sia, we organized our great flagship conference - IEMT-EMAP2016 (the 37th International Electronics Manufacturing Technology Conference and 18th Electronic Materials and Packaging Conference), co-sponsored by CPMT Santa Clara that was held at G-Hotel, Penang, back to September 2016. Despite a challenging global economy, the conference was held successfully with an encouraging number of greater than 400 electronic packaging experts; jointly attended by overseas participants from Asia Pacific, Europe and North America and local members alike. The IEMT-EMAP2016 has established itself as THE forum for knowledge exchange and professional networking in the APAC region. CPMT spearheaded the conference with the tagline crafted by Prof. Rickey Lee, our Senior Previous President of CPMT - **C**onnecting **P**eople and **M**achine **T**ogether. Furthermore, our chapter also sponsored several best Final Year Projects at University of Nottingham Malaysia Campus, University Malaysia Perlis and Inti International University and College. The sponsorship is targeted to encourage greater awareness amongst students of career opportunities in microelectronics components, packaging and manufacturing technology as well as motivate them to excel in it. We partnered closely with CREST for a good collaboration opportunity in Industry Academic Forum to develop some potential electronic packaging related project clusters. On top of all that, we are heavily engaged in some major regional conferences like IMPACT (Taiwan) and EPTC (S'pore) to jointly develop the R10 region and link that back up to HQ CPMT Santa Clara's vision for the Society.

As mentioned, the accelerated growth in the new trend of "Internet of Things" (IoT) resulted in countless opportunities for components and packaging technologists. We look forward to your participation and continuous support in our CPMT Chapter to make our industry more vibrant and representative of our industry in Malaysia and surrounding regions. We will discuss more in the coming Jan' 2017 AGM for some of the key events to be held for our distinguish members which includes bi-annual technical workshops, membership loyalty programs, permeation of information amongst members and many more. I wish you all a great year ahead for 2017! See you in the upcoming AGM.

IEEE-CPMT IMPACT Taiwan Conference (Taipei, 26th to 28th Oct 2016)

International Microsystems, Packaging, Assembly and Circuit Technology (IMPACT) is a joint international conference consisting of iMAPS All Asia Conference (IAAC) organized by IEEE CPMT-Taipei, iMAPS-Taiwan, ITRI and TPCA. IEEE Malaysia CPMT chapter was honored to have its multiple submissions requested in both the Invited Papers and Oral Presentations categories. CPMT Malaysia was represented by Shaw Fong Wong (from Intel Technology) who presented 2 invited papers entitled "Trends and Opportunity in Malaysia IoV" and "Packaging as IP Differentiator". The other 5 oral presentations were presented by Malaysia delegates, from Altera-Intel, Jabil and Freescale-NXP. The overall successful IMPACT conference had become a vortex of valuable resource under various APAC region CPMT chapters' contribution and participation; a hallmark of strong collaboration forum between CPMT Malaysia and Taipei on continuous technical sharing and professional development.

Figure 1 : *Get together session with Taiwan delegates, iNEMI representatives and keynote speakers*

Figure 2 : *The view of well-attended keynote lecture*

IEEE CPMT Malaysia Best Final Year Project (FYP) Undergraduate Prizes 2016

Dr. Siow Kim Shyong from National University of Malaysia was the Project Manager for this program which was targeted to encourage greater awareness amongst students of career opportunities in microelectronics components, packaging and manufacturing technology as well as motivate them to excel in it. Winners received RM500 cash and a book valued at RM300 donated to their respective university by Rolf Aschenbrenner (Fraunhoffer IZM). In 2016, 3 students won Best FYP Undergraduate Prizes. They were Mah Chee Weng from University of Nottingham Malaysia Campus with the topic "*Modeling of an Ocean Thermal Energy Conversion System*"; Norhafifah Binti Zainal Azlin from University Malaysia Perlis with the topic "*The Effect of Thermal Aging on Intermetallic Compound Growth of Lead free SAC and SAC/Activated Carbon Composite Solder Joint*"; Chin Kim Keat from Inti International University and College with the topic "*Cryptanalysis using Genetic Algorithm*". A big Congratulations to the 3 winners!! Well Done!

Figure 1: *Dr Chee CK witnessed the presentation of Degree by Pro Vice-Chancellor Prof Robert Parkin to Chin Kim Keat*

Figure 2: *LEFT: Dr Khairel Rafezi Bin Ahmad, Dr Luqman Bin Musa and Norhafifah Binti Zainal Azlin. RIGHT: Dr Chee CK presenting award to Mah Chee Weng*

Summary of 37th IEMT & 18th EMAP 2016 Conference, Georgetown, Penang

(Compiled by Guat Li Chew, Dr. Tze Yang Hin, Ir. Dr. Wong Yew Hoong & Dr. Choong Kooi Chee)

Voted 2nd Top Tourist destination for 2017 by CNN, Penang was the Asian center of the packaging universe in the month of September 2016. Its multicultural and picturesque historical setting coupled with its reputation as having Asia's best street food proved to be an added bonus for conference participants and organizing committee alike. Amongst the clatter of Asam Laksa bowls, Nasi Kandar plates and abundant clinking of Teh Tarik glasses, rife conversations were on-going about the future of the globally connected world via numerous type devices in terms of security and possibilities. Packaging these devices at an affordable cost is a major challenge facing members of the Components, Packaging and Manufacturing technology (CPMT) society.

Since 2006, the IEEE CPMT Malaysia chapter was the main advocate of International Electronics Manufacturing Technology (IEMT) conferences, in conjunction with co-sponsor CPMT Santa Clara. The organizing committee members were volunteers from local multinational semiconductor companies such as Intel Technology, Infineon, ON Semiconductor, Carsem, Lumileds, Unisem, NXP, Peters, Indium and semi-governmental body CREST. The local universities members in this year's organizing committee were from Universiti Kebangsaan Malaysia (UKM), Universiti Teknologi Malaysia (UTM) and Universiti Sains Malaysia (USM). This year, the 37th International Electronics Manufacturing Technology Conference was jointly organized in concurrent with the 18th Electronic Materials and Packaging (EMAP) Conference on the beautiful city of Penang, a UESCO World Heritage site. G-Hotel was the elegant sea-front venue of the combined conference.

***Figure 1**: The IEMT2016 organizing committee with their charismatic conference chair in the back row*

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The conference was proud to have invited industry-leaders to share the latest industry trend and technology in its 5 short courses, 8 keynotes and 16 invited papers. There were 80

abstracts accepted for oral papers as well as interactive poster papers. The conference had always attracted >60% of the total abstracts from the industry and 30-40% of those were from abroad. This has served well for the conference as a platform for technology and knowledge exchanges within the electronic manufacturing community. Back in IEMT2014, the focus was on Internet-of-Things (IoT) and its application. This year conference's theme was "Packaging the IoT", an extension of the 2014 topic. This round, the focus was more skewed to the fundamental technologies that drive the development and enabling of IoT hierarchy. The conference provided insights into core technologies such as wire bonding material and processes, chip-to-package interconnection, solder materials and other materials development trends, and new reliability requirements. The new entrant to IEMT-EMAP conference series this year was the inclusion of LED packaging and the optical characteristics. All in all, this was the first time that the Conference had more than 450 participants, a major achievement in terms of attendance. Kudos to the core organizing team, especially the Publicity and Publication Team! Furthermore, there was a total of 21 table top exhibits and a record-breaking sponsorship this year – Fabulous job by the Sponsorship & Exhibit Team. Logistics and management of last minute changes, walk-ins, change of players were handled magnificently by the Secretariat team headed by Wee Teck and Hafiza! Not forgetting the excellent Program Book designed by the Program Chairs. Under the strong leadership of Dr Hin, all these various teams coalesced to handle a much larger crowd than expected.

The three-day event started with four short-course workshops for 144 people on the initial day. These courses were given by renowned technical experts invited from overseas. The courses were *Chip to Package Interconnect Technology: Fundamentals and Future Trend* by Mr. Charlie Lu Tsung-Hsing (Taiwan Printed Circuit Association), *Fan-Out Wafer Level Packaging (FO-WLP) – Innovative and Novel Solutions of Advanced Packaging* by Dr. Seung Wook Yoon (Director of Products & Technology Marketing STATS ChipPac-JCET, Singapore), *Copper Ball Bonding Materials, Intermetallics & Reliability* by Dr. Christopher Breach (ProMat Consultants, Singapore), *Achieving High Reliability for Lead-Free Solder Joints* by Dr. Ning-Cheng Lee (Vice President of Technology, Indium Corporation) and *Trends in Material Development – Upcoming Requirements concerning Reliability* by Dr. Klaus Mueller (Senior Principal Infineon Germany).

***Figure 2**: 1st Day Short-course instructors and students listening attentively to the instructors.*

The remaining two days comprised keynote speeches, invited talks, paper and poster presentation sessions from leaders of the industry. The conference was opened with a short address given by the IEEE CPMT President representative Dr. William T. Chen (ASE Group USA) who spoke on *Heterogeneous Integration, expounding on the Roadmap to the Brave New Interconnected World*. It was then followed by a series of excellent keynotes, namely the *Development in Internet of Things (IoT) and Opportunities for "Packaging the Iot"* by none other

than Mr. Eric Chan (Intel Corporation Malaysia), *Panel Level Embedding for Power and Sensor Applications* by Dr. Rolf Aschenbrenner (Fraunhofer Institute for Reliability, Microintegration Berlin (IZM), Germany), *Anisotropic Conductive Films(ACFs): Interconnection Technology for Wearable Electronics Applications* by Professor Kyung Wook Paik (KAIST, Korea) and *The Future of Power Device Packaging: Materials and Assembly Processes* by Dr. Andrew Christopher Mackie (Indium Corp, USA) on Day 2 of the Conference. Final day of the conference witnessed additional exceptional keynotes such as *Material Challenges for Optoelectronic Packages in Lighting Applications* by Dr. David Lacey (R&D Director of OSRAM Opto Semiconductors Malaysia), *Technological Challenges and Market Trends for Power Packaging* by Dr. Pierric Gueguen (Yole Dévelopment, France) and the closing keynote address *Packaging and Integration Technologies for the Era of Internet of Things* by Professor Ricky Lee Shi-Wei (HKUST Hong Kong). Dr. Lacey's keynote was especially interesting to the participants coming from the LED industry as it was clear, simple and the futuristic work displayed was very impressive.

The conference's four-track oral presentation sessions consisted of 64 selected papers and 16 invited papers from prominent guest speakers. Eighteen posters were presented by industry technologists at the main hall along with the exhibitions. The conference provided an opportunity for the participants to mingle and build network in various areas of electronic packaging.

***Figure 3**: (from left to right) Opening speech by Dr. Hin Tze Yang (Conference Chair), captive audience in Main Conference Hall.*

***Figure 4**: Small sample of the myriad of Exhibitors displaying their products and services, including QDOS, IEEE, Atotech, IEEE Student Body, TechSearch International, Loctite Semiconductor Technologies*

***Figure 5**: (left to right) Poster Display showcasing "Addressing the Challenges of Sensitive Die Technologies to Enable Copper Wire Bonding" by Manny Ramos et al from ON Semiconductor Philippines; Poster Display showcasing "Development of Conductive Die Attach Film Application Process with Variable Wafer Back Metallization and Substrate Surface Type" by Tan Kai Chat et al from ON Semiconductor Malaysia*

IEMT has always been the battle ground for its prestigious awards. There are 3 Award categories - Best Industry Paper Awards, Best Student Paper Awards and Best Poster Paper Awards. The judges for these awards were experts in the areas of electronic packaging – Dr. Rolf Aschenbrenner, Dr. Klaus Mueller, Mr. William Chen and Dr. Sung Yi. The Best Industry Paper Award went to K.H. Loh et al of Carsem for "*Qualification and Application of Pressure-less Sinter Silver Epoxy"* with the runner up being Min Fee Tai et al from Atotech and UTeM with their submission, "*EMI Shielding Performance by Metal Plating on Mold Compound"*. The Best Student Award went to Robin Ong & Kuan Yew Cheong from USM for their work on "*Non-Destructive Electrical Test Detection On Copper Wire Micro Crack Weld Defect In Semiconductor"* with the Merit Award going to Nadhrah Murad et al for their submission "*Effect of Sintering Parameters on Properties of Sn-4.0Ag-0.5Cu-1.0Ni Solder Alloy"*. The Best Poster was awarded to Chong Seng Foo & Jui Ang Tan from Intel Malaysia for their poster *"Cost Savings Through Innovative and LEAN Engineering Approach for Wireless Modules"*. The runner-up Poster Award was bestowed to Cheng Guan Ong et al from Infineon and UTem for their poster entitled "*Effect of Cu Based Complexes on EFTECH64 and C194 Cu Alloy"*. Congratulations to all the award winners!

***Figure 6**: Awards Judges and Winners of IEMT2016 (left to right): Dr. CK Chee, KH Law & Dr. Klaus Mueller (Best Industry Paper Category); Dr. CK Chee, Dr. Rolf Aschenbrenner & Robin Ong (Best Student Paper Category); Dr. CK Chee, Prof. Ricky Lee, Chong Seng Foo & Jui Ang Tan (Best Poster Category).*

***Figure 7**: IEMT-EMAP Participants just want to have fun!! Prestigious Industry leaders mingling with students and young working engineers from various companies.*

No conference was complete without a Gala Dinner. The participants were treated to a sumptuous Buffet Seafood dinner at the 59Sixty situated at the pinnacle of Komtar, the tallest building in Penang. The Penang Heritage scenery was an eye-opener with view of the city layout, the old heritage buildings and the winding quaint Penang lanes. During the dinner, the participants were entertained with a Lion Dance, which was a challenge, given the space constraints, and cultural dance show from the diverse tribes and racial mix. A few of the participants were invited on stage to dance the bamboo dance where the participants had to jump between bamboo poles and not get entangled in the poles. Dr. Chee led our visitor volunteers in demonstrating this – the Malaysian equivalent of pole dancing! Bravo Dr. Chee! Many thanks to all our participants and visitors who made this event a major success!! We'll see you all in the 2018 IEMT Conference!

***Figure 8**: Group photo of Invited Guests and Organising committee*

Figure 9*: (Top left to bottom right) Georgetown city layout from the top of Komtar, Challenging Lion Dance in space constrained restaurant, Panaromic view from 59Sixty Restaurant, Malaysian bamboo Pole Dancing, Chinese Lion Dance Performance*

IEEE R10 Chapter Chair Meeting at EPTC Singapore

A regional IEEE Chapter Chair R10 meeting was held in Singapore in conjunction with the 18th Electronics Packaging Conference (EPTC 2016). The Malaysian Chapter was represented at the meeting by Azhar Aripin, the treasurer of the chapter. The meeting was held on the 2nd of December, 2016. The director of Region 10, Mr. Yasumitsu Orii chaired the meeting which was also attended by the President if IEEE Society Jean Trewhella. Mr. Orii presented the opening speech and welcomed all the participants. He indicated he would like to see more collaboration work between Chapters in the future. Jean stressed the importance of increasing membership numbers as part of the recruitment drive initiative. The group shared their reasons for remaining in CPMT to try and identify the main relevance of the society to the individual as an initial step towards retention stragey formulation. Jean also updated the team that during the recent BoJ meeting, they have decided to change CPMT name to something more representative of the chapter activities. Currently, CPMT which stands for Component, Packaging and Manufacturing Technology, is the longest chapter name in IEEE. CPMT will make an announcement of the new name soon. Then all the chapter chairs updated their chapter activities and plan for 2016. Few chapter chairs who were not able to be present in the R10 meeting have also shared their chapter activities through the director Region 10, Mr. Yasumitsu Orii who presented on their behalf. At the end of the meeting, a group photo was taken.

Figure 1: *Participants of 2016 Chapter Chair meeting of R10 at EPTC Singapore.*

Upcoming CPMT Conferences & Meetings

Networking and constant knowledge advancement opportunities are always an important part of any conference. CPMT chapters have lined up an outstanding program with top tier speakers and timely topics for 2017. Below is a sampling. Mark the dates!

CPMT CONFERENCES IN 2017:

2017 Pan Pacific Microelectronics Symposium (Pan Pacific) Kauai, HI USA	Feb 6, 2017 - Feb 9, 2017
2017 18th International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE) Dresden, Germany	Apr 2, 2017 - Apr 5, 2017
2017 IEEE International Workshop On Integrated Power Packaging (IWIPP) Delft, Netherlands	Apr 5, 2017 - Apr 7, 2017
2017 IEEE 21st Workshop on Signal and Power Integrity (SPI) Baveno (VB), Italy	May 7, 2017 - May 10, 2017
2017 28th Annual SEMI Advanced Semiconductor Manufacturing Conference (ASMC) Saratoga Springs, NY USA	May 15, 2017 - May 18, 2017
2017 16th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems (ITherm) Orlando, FL USA	May 30, 2017 - Jun 2, 2017
2017 IEEE 67th Electronic Components and Technology Conference (ECTC) Orlando, FL USA	May 30, 2017 - Jun 2, 2017
2017 7th IEEE International Workshop on Advances in Sensors and Interfaces (IWASI) Vieste, Italy Abstract Submission Date: May 1, 2017	Jun 15, 2017 - Jun 16, 2017
2017 23rd International Workshop on Thermal Investigations of ICs and Systems (THERMINIC) Amsterdam, Netherlands	Sep 27, 2017 - Sep 29, 2017
2017 IEEE Holm Conference on Electrical Contacts CO, USA	Oct 1, 2017 - Oct 4, 2017

Pan Pacific Microelectronics Symposium

February 6-9, 2017
Sheraton Poipu Kauai Resort
Kauai, Hawaii

The Pan Pacific Microelectronics Symposium promotes international technical interchange and provides a premier forum for networking among microelectronics professionals and business leaders throughout the world.

Pan Pac Provides You the Latest Research On

- 3D/Heterogeneous Integration
- Emerging Technologies
- Green Electronics
- High Performance Low I/O
- Internet of Things (IoT)
- Material Advances
- Nanotechnology
- Photonics
- Reliability and Quality
- Trends, Roadmaps, and more...

"Pan Pac is unique because of the high-quality attendees and exceptional presentations it draws, as well as the casual and social atmosphere that permeates the conference."

David Raby, *STI Electronics, Inc.*

2017 International Conference on Electronics Packaging (ICEP2017)
Date: April 19-22, 2017
Venue: Takionoyu Hotel, Tendo, Yamagata

Call for Papers

The submission deadline is extended to October 10, 2016.

We are waiting for your abstract submission.

Please prepare an abstract using the attached template to help us better evaluate your submission. The abstract should contain about 1 page of text and 1 page for supporting figures and tables, with a total length of 2 pages at maximum.
Figures and tables to support the point of the paper will receive positive considerations. Your abstract will be used for review purpose only and will not be included in the conference proceeding.
Thank you very much for your contribution!

Yamagata MICE Navi

YAMAGATA Prefecture in Japan is famous for its hot springs, beautiful frosted-covered trees as Great nature entertainment. Even among those, 7 cities and 7 towns are very attractive areas to enjoy sightseeing and nature. 'Yamagata MICE Navi' is a support application for participating in a convention and planning a business travel. 'MICE' is 'business travel' which now attracts worldwide attention, a newly coined word to combine head-letters from following words; Meeting, Incentive tour, Convention and Exhibition. What is the biggest difference form a package tour is original and special planning and service. Yamagata Prefecture has ideal facilities and events for business travel to hold convention such as international meetings or national tournaments, nothing other than attractive sightseeing and nature! 'Yamagata MICE Navi' willingly offer information for organizers and participants in Yamagata to feel comfortable and join conveniently.

ECTC 2017
IEEE Electronic Component and Technology Conference

Walt Disney World Swan and Dolphin Resort
Lake Buena Vista, Florida USA
May 30 - June 2, 2017

Located in the heart of the most magical place on earth, the Walt Disney World Swan and Dolphin Resort provides a truly extraordinary backdrop for a meeting. Beautiful tropical landscaping, tranquil waterways and classic art and architecture work together to create a stunning landmark in the midst of one of the most spectacular places on earth.

The Electronic Components and Technology Conference (ECTC) is the premier international event that brings together the best in packaging, components and microelectronic systems science, technology and education in an environment of cooperation and technical exchange. ECTC is sponsored by the Components, Packaging and Manufacturing Technology (CPMT) Society of the IEEE. The 2017 ECTC will be held at The Walt Disney World Swan and Dolphin Resort, Lake Buena Vista, Florida, USA, during May 30 – June 2, 2017, featuring about 40 technical sessions (oral presentations, interactive presentations, and student posters), 16 professional development courses, a panel discussion, a plenary session, a CPMT Seminar, and a technology corner for exhibitors.

The technical program contains papers covering leading edge developments and technical innovations across the packaging spectrum. Topics include advanced packaging, modeling and simulation, optoelectronics, interconnections, materials and processing, applied reliability, assembly and manufacturing technology, components and RF, and emerging technologies. Both poster and presentation formats are used. Special papers presented at the ECTC will be awarded the Intel Best Student Paper Award and best and outstanding paper awards.

The Professional Development Courses offer state-of-the-art technology reviews and updates in a condensed half-day format. Topics cover a wide range of technologies.

The Panel Discussion, Plenary Session, and CPMT Seminar in the evenings offer a format that allows for ample exchange and dialogue between the presenters and audience. They provide the conference participants the opportunity to gain the insight and perspective of technical and business leaders.

The Technology Corner complements the Technical Program by providing companies the opportunity to exhibit their products and services in an environment that enables discussion and interaction with the managers and engineers attending ECTC.

The ECTC would not be possible without the sponsorship of the IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society, numerous corporate participants and sponsors, and the time and energy of the more than 200 engineers and scientists on the ECTC Executive and Program Committees.

1st Call for Papers

ICEPT2017

The 18th International Conference on Electronic Packaging Technology

August 16~19, 2017

Harbin，China

The 18th International Conference on Electronic Packaging Technology (ICEPT 2017) will be held in **Harbin, China, from August 16 to 19, 2017**. The ICEPT 2017 is organized by Chinese Institute of Electronics (CIE), Institute of Microelectronics of Chinese Academy of Sciences (IMECAS), IEEE-CPMT, Electronic Manufacturing and Packaging Technology Society of Chinese Institute of Electronics (CIE-EMPT) and co-organized by Harbin Institute of Technology (HIT). As one of the most famous international conferences on electronic packaging technology, the conference has received strong support from IEEE CPMT and active involvement from IMAPS and iNEMI, and was highly appreciated by CIE and China Association for Science and Technology (CAST).

ICEPT 2017 is a **four-day event**, featuring technical sessions, invited talks, professional development courses, exhibition, and social networking activities. It aims to cover the latest technological developments in electronic packaging, manufacturing and packaging equipment, and provide opportunities to explore the trends of research and development, as well as business in China.

CONFERENCE THEMES

- **Advanced Packaging:** BGA, wafer-level packaging, flip chip, 3D packaging, advanced packaging substrate technologies, system integration, heterogenous/hybrid integration, system level packaging.
- **Packaging Materials & Processes:** Green materials, nano-materials, other novel materials for packaging, and packaging/assembly processes for related packaging materials.
- **Packaging Design and Modeling:** Design, modeling, methodology, and simulation for system integration and packaging; methodology and simulation for electrical/thermal/optical/mechanical models, multi-scale and multi-physics modeling, process simulation.
- **Interconnect technologies:** TSV, bumping technologies, high density inter-connection technologies, bonding technologies, interposer, non-conventional inter-connection technologies.
- **Advanced Manufacturing Technologies and Packaging Equipment:** Packaging/assembly manufacturing technologies and equipments, on-line measurement and test technologies, charactorization technologies and equipments.
- **Quality & Reliability:** Test technologies for packaging, quality monitoring and evaluation, methodologies for reliability data collection and analysis, reliability modeling, life prediction, failure analysis and non-destructive diagnose.
- **Solid State Lighting Packaging & Integration:** Novel technologies for LED packaging, methodologies for design, manufacturing and test of high power LED module, LED packaging/integration technologies.
- **High-speed & High-frenquency and Microwave and Power Electronics Packaging:** Components and modules for high speed & high frequency, microwave component and device, power device, automobile electronics high-temperature electronic component and device.
- **Emerging Technologies:** MEMS/NEMS, MOEMS, optoelectronics, medical electronic device and integration, wearable/flexible electronics packaging, internet of things, sensors/actuators, nano-devices, etc.

IMPORTANT DATES

- **March 31, 2017** — **Deadline for Submission of Abstract**
- **April 15, 2017** — **Notification of Abstract Acceptance**
- **May 20, 2017** — **Deadline for Submission of Full Paper**
- **June 20, 2017** — **Notification of Full Paper Acceptance**
- **June 30, 2017** — **Deadline of Final Paper Submission**

SUBMISSION OF ABSTRACT

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, conclusions, and important references of the work. All abstracts and papers must be in English and should be submitted through online submission system.

The instructions for abstract submission can be downloaded at the conference website **http://www.icept.org**. All accepted papers will be indexed by IEEE Xplore. Selected papers will be recommended for publication in related IEEE/CPMT journals.

BEST PAPER AWARD

The conference proceeding is an official IEEE publication. Best Conference and Student Papers will be selected and awarded at the conference.

CALL FOR SHORT COURSES

The conference program includes professional development courses (PDC), and the leading experts in the field may e-mail to icept2017@hit.edu.cn for details.

CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components, software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may e-mail to icept2017@hit.edu.cn for details.

Conference Website: http://www.icept.org/en

Conference E-mail: icept2017@hit.edu.cn

ABOUT Harbin

Harbin, the capital and largest city of Heilongjiang province in northestern China, is famous as the *Ice City* for its well-known winter tourism and recreations. Also, Harbin Summer Music Concert is a national concert festival, which is held in August for a period of ten days. The city has been voted "China Top Touist City" and appointed a "City of Music" by the United Nations.

Hosted By CIE, IMECAS

Technically Sponsored By EMPT CIE--Electronic Manufacturing and Packaging Technology Society; CPMT IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

Organized By 哈爾濱工業大學 HARBIN INSTITUTE OF TECHNOLOGY

Merry Christmas and Happy New Year 2017!

IEEE-CPMT Malaysia Chapter wishes all Merry Christmas and Happy Holidays! May your stockings be filled with gifts and surprises and may your home be filled with love and happiness. Have a blessed Christmas!

Hey all… A new year is knocking on the door. 2016 is history and the world will enter the New Year 2017. So be ready to yell and welcome "A Happy New Year 2017". Wish you a great, prosperous, blissful, healthy, bright, delightful, energetic and extremely Happy New Year!

Some Important References:

- Official IEEE website: http://www.ieee.org
- Official IEEE/CPMT website (HQ): http://cpmt.ieee.org
- **Official IEEE/CPMT website (M'sia Chapter) – leverage IEMT-EMAP2016 :** http://ewh.ieee.org/r10/malaysia/cpmt/